

## Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

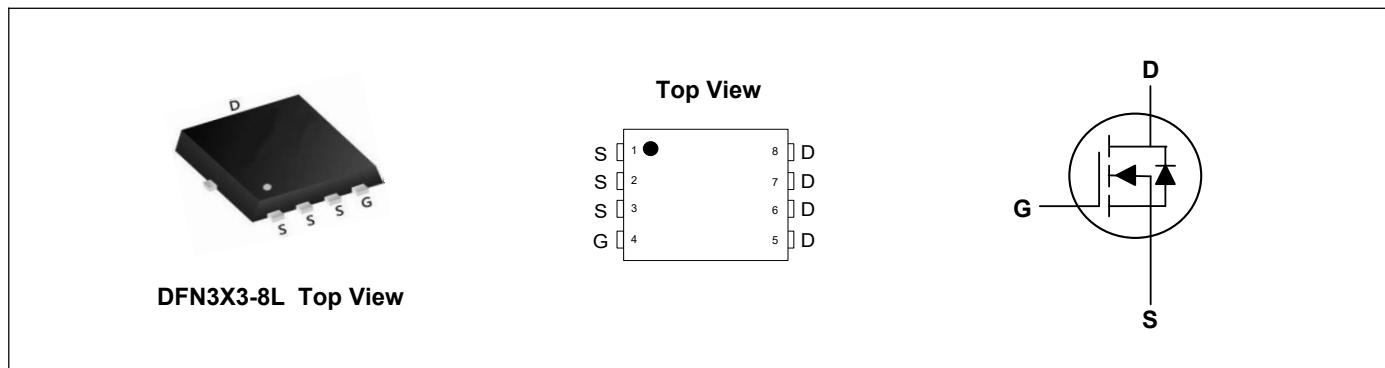
## Product Summary



$V_{DS}$	30	V
$I_D$	50	A
$R_{DS(ON)}$ (at $V_{GS}=10V$ )	4.9	mΩ
$R_{DS(ON)}$ (at $V_{GS}=4.5V$ )	5.5	mΩ

## Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch



## Absolute Maximum Ratings( $T_c=25^\circ C$ , unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current <sup>1</sup>	$I_D @ T_c = 25^\circ C$	50	A
Continuous Drain Current <sup>1</sup>	$I_D @ T_c = 100^\circ C$	32	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	150	A
Single Pulse Avalanche Energy <sup>3</sup>	EAS	125	mJ
Avalanche Current	$I_{AS}$	50	A
Total Power Dissipation <sup>4</sup>	$P_D @ T_c = 25^\circ C$	31	W
Storage Temperature Range	$T_{STG}$	-55 to 150	°C
Operating Junction Temperature Range	$T_J$	-55 to 150	°C

## Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient <sup>1</sup>	$R_{\theta JA}$	---	65	°C/W
Thermal Resistance Junction-Case <sup>1</sup>	$R_{\theta JC}$	---	4	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	30	---	---	V
Static Drain-Source On-Resistance <sup>2</sup>	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}$ , $I_D=12\text{A}$	---	4.2	4.9	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=12\text{A}$	---	4.6	5.5	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}$ , $I_D=10\text{A}$	---	5.5	7.5	$\text{m}\Omega$
		$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	0.4	---	1.0	V
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=5\text{V}$ , $I_D=12\text{A}$	---	25	---	S
Gate Resistance	$R_g$	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1.4	---	$\Omega$
Total Gate Charge (4.5V)	$Q_g$	$V_{\text{DS}}=20\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_D=12\text{A}$	---	32	---	$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$		---	6.1	---	
Gate-Drain Charge	$Q_{\text{gd}}$		---	14	---	
Turn-On Delay Time	$T_{\text{d(on)}}$		---	12	---	$\text{ns}$
Rise Time	$T_r$	$V_{\text{DD}}=15\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=1.5\Omega$ , $I_D=12\text{A}$	---	46	---	
Turn-Off Delay Time	$T_{\text{d(off)}}$		---	33	---	
Fall Time	$T_f$		---	7.5	---	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	3100	---	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		---	405	---	
Reverse Transfer Capacitance	$C_{\text{rss}}$		---	310	---	

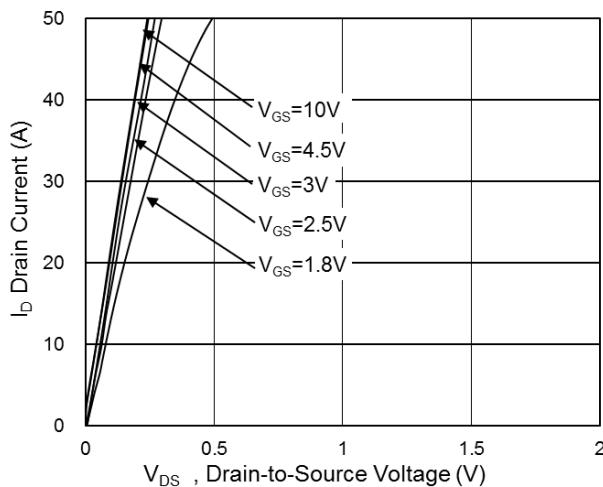
**Drain-Source Diode Characteristics**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current <sup>1,5</sup>	$I_s$	$V_G=V_D=0\text{V}$ , Force Current	---	---	50	A
Pulsed Source Current <sup>2,5</sup>	$I_{\text{SM}}$		---	---	150	A
Diode Forward Voltage <sup>2</sup>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V

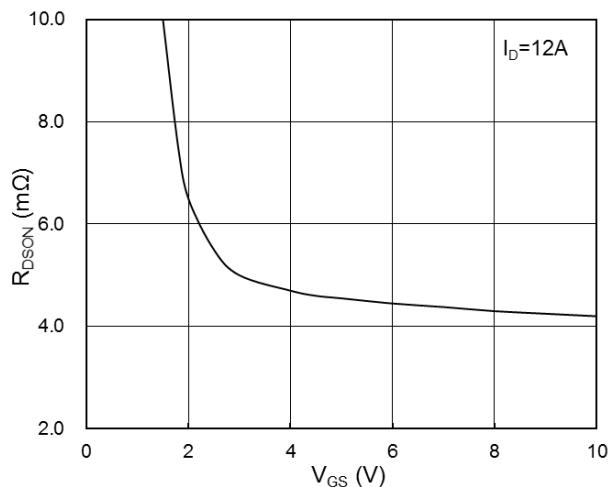
**Note:**

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $L=0.1\text{mH}$ , $I_{\text{AS}}=50\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

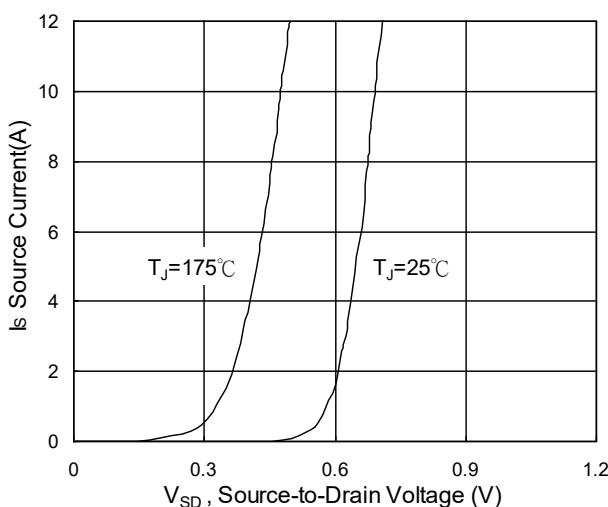
## Typical Characteristics



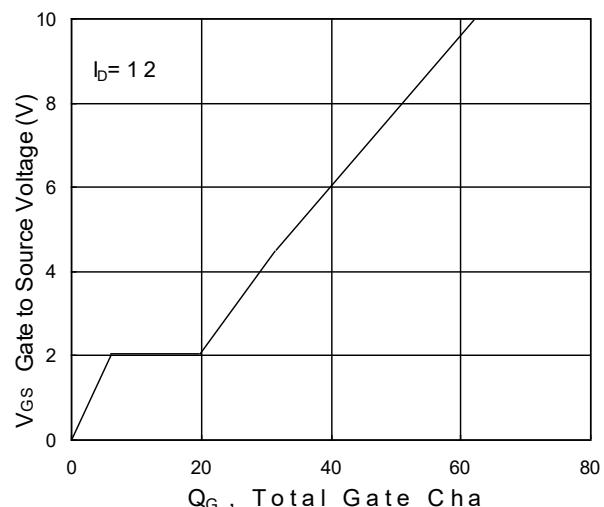
**Fig.1 Typical Output Characteristics**



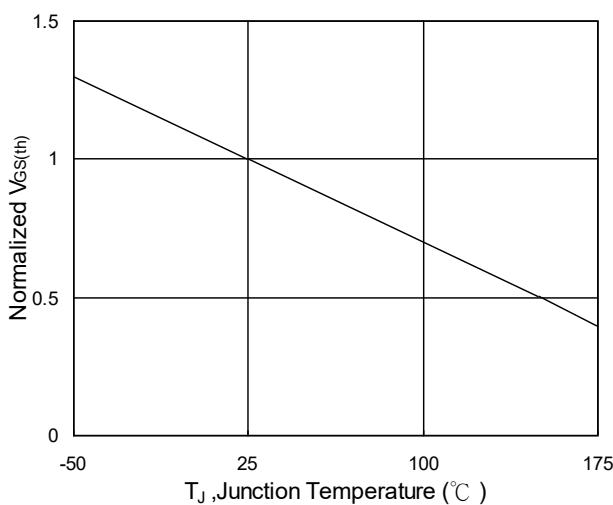
**Fig.2 On-Resistance vs. G-S Voltage**



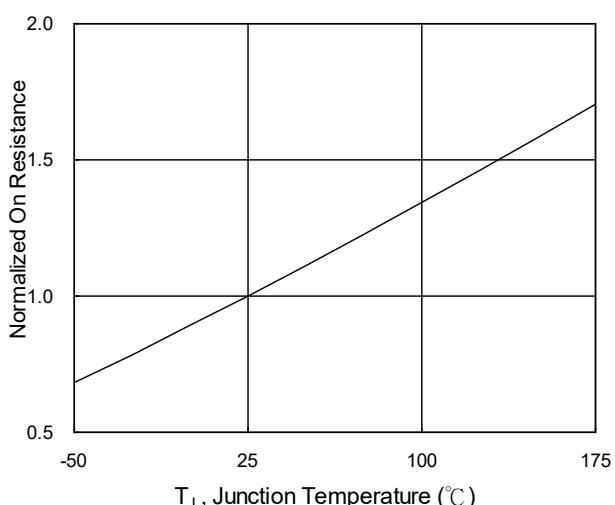
**Fig.3 Forward Characteristics of Reverse**



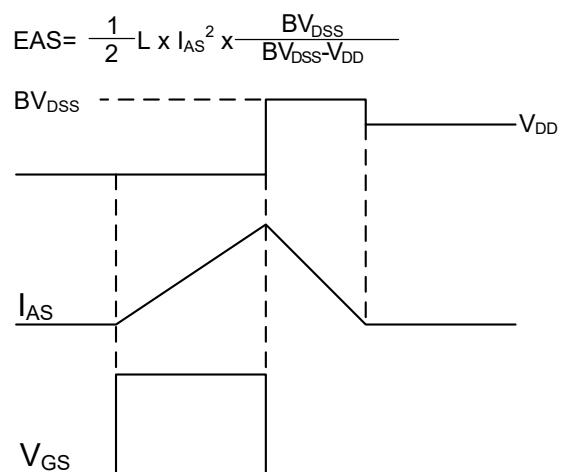
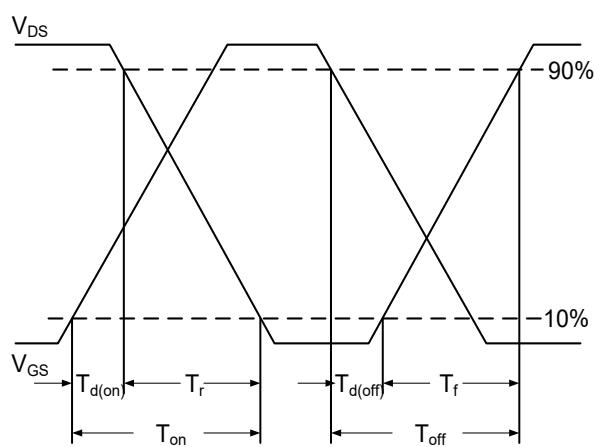
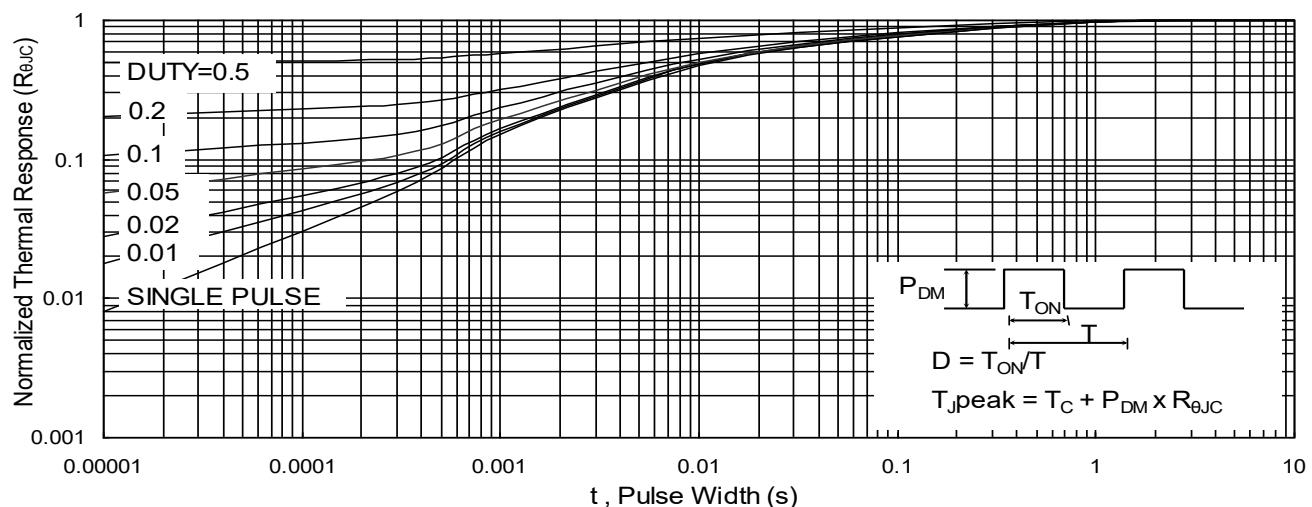
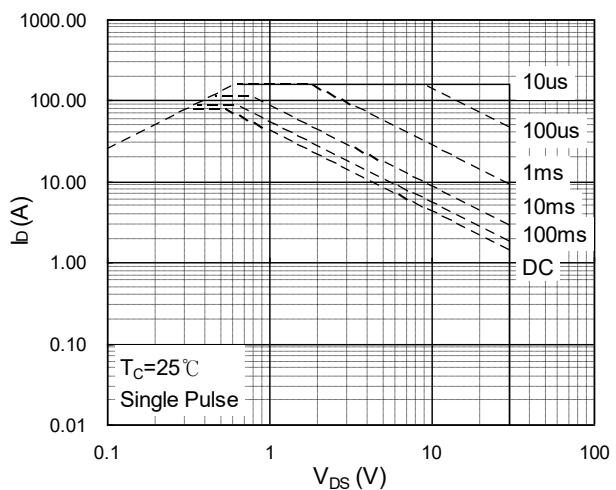
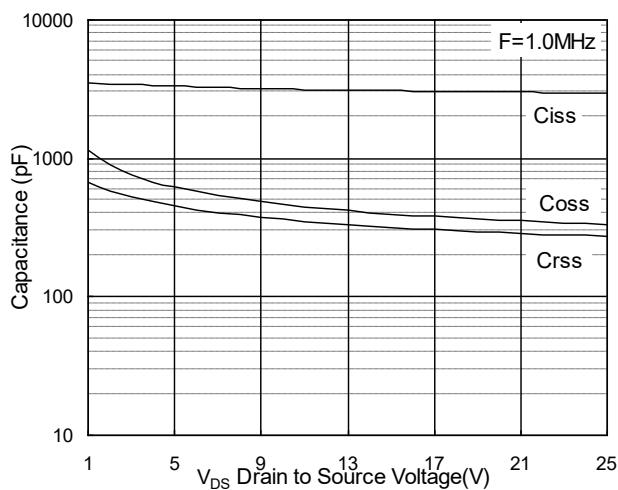
**Fig.4 Gate-Charge Characteristics**



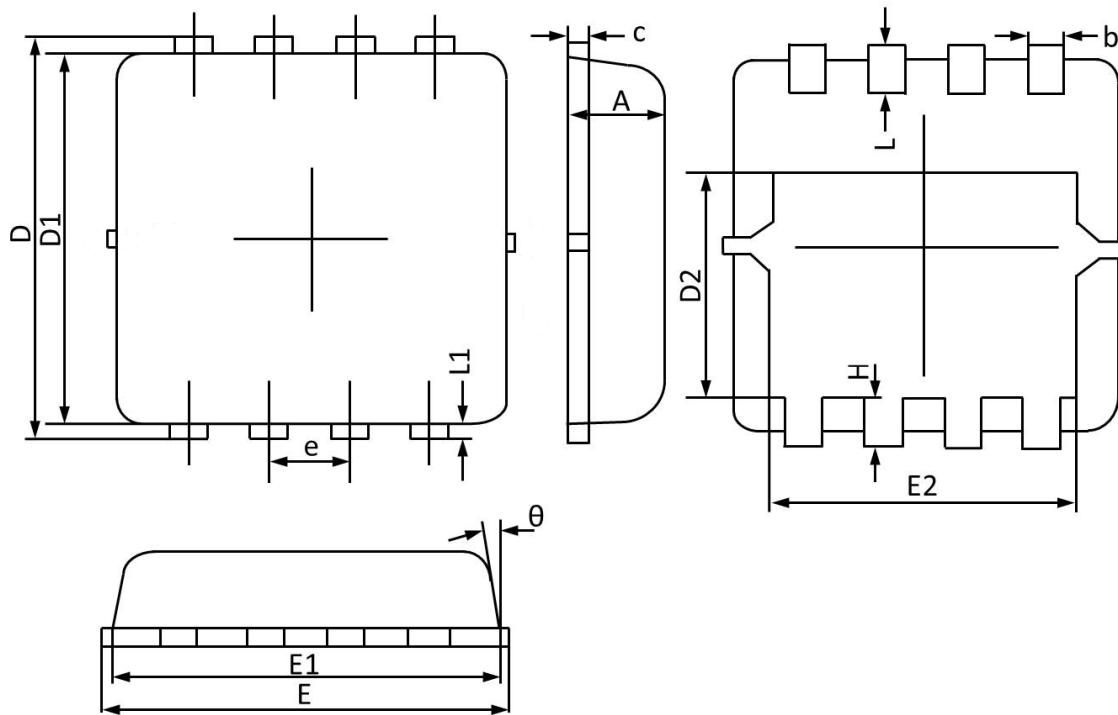
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**



## DFN3X3-8L Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	0.70	0.75	0.85	E1	2.90	3.10	3.25
b	0.24	0.30	0.35	E2	2.35	2.50	2.60
c	0.10	0.17	0.25	e	0.65 BSC		
D	3.10	3.30	3.45	H	0.30	0.40	0.50
D1	2.90	3.05	3.20	L	0.30	0.40	0.50
D2	1.45	1.70	1.95	L1	--	0.13	--
E	3.05	3.25	3.40	θ	0°		14°